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PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Serial No.: (Divisional of U.S. Serial No. 09/322,416 which is  
a Continuation of U.S. Serial No. 09/187,617)  
Filed: July 3, 2001  
Applicant: Austin et al.  
Title: **METHOD FOR VACUUM ENCAPSULATION OF  
SEMICONDUCTOR CHIP PACKAGES**  
Our Ref. No.: NOR-865B

Cincinnati, OH

July 3, 2001

Assistant Commissioner for Patents  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Sir:

Prior to examination of the above-identified application, please  
amend the application as follows:

**In the Specification:**

On page 1, line 1, please insert the following: [The present

application is a divisional of co-pending U.S. Serial No. 09/322,416, filed  
*and now U.S. Patent No. 6,284,173,*  
May 28, 1999, which is a continuation of U.S. Serial No. 09/187,617, filed  
*and now abandoned,*  
November 6, 1998, the disclosures of which are hereby incorporated herein  
by reference in their entirety.--

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